

RECEIVED
CENTRAL FAX CENTER

MAY 29 2008

In the Claims:

1. (Original) An electronic device (1)
- with a base plate (2),
- with an electronics housing (3) which is connected to
the base plate (2), with at least one bond contact
bearer (5),
characterised in that the bond contact bearer (5) is
supported on the base plate (2) by a supporting body (6) in
such a manner that the supporting body (6) exerts a
pretension force onto the bond contact bearer (5).
2. (Original) An electronic device according to claim 1,
characterised in that a projection of the supporting body
(6) above the base plate (2) is greater than the distance
between the bond contact bearer (5) and the base plate (2).

Claims 3 and 4 (Canceled).

5. (Currently amended) A procedure for bonding ~~[[an]]~~ the
electronic device (1) ~~with the following procedural stages:~~
according to claim 1, comprising the steps:
~~provision of a~~
providing the base plate (2),
~~connection of an~~
connecting the electronics housing (3) via ~~[[a]]~~ the
supporting body (6) with the base plate (2) in such a

manner that the supporting body (6) exerts ~~[[a]]~~ the
pretension force onto the bond contact bearer (5), and

~~creation of~~

creating a bond connection between the bond contact
bearer (5) of the electronics housing (3) and an additional
bond contact bearer.

6. (Previously presented) An electronic device according to
claim 1, characterized in that the supporting body (6)
represents a separate component from the base plate (2),
which is mechanically connected to the electronics housing
(3).

7. (Previously presented) An electronic device according to
claim 1, characterized in that the supporting body (6) is
designed as a projecting ring or as a plurality of
projecting individual segments.

[RESPONSE CONTINUES ON NEXT PAGE]